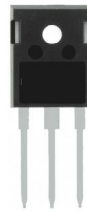


## Main Product Characteristics

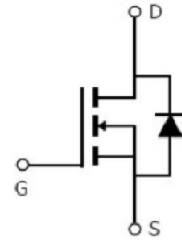
$V_{DSS}$	600V
$R_{DS(on)}$	0.2ohm(typ.)
$I_D$	20A



TO247



Marking and Pin Assignment



Schematic Diagram

## Features and Benefits

- High dv/dt and avalanche capabilities
- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance
- Lead free product



## Description

The SSF20N60H series MOSFET is a new technology, which combines an innovative super junction technology and advance process. This new technology achieves low  $R_{DS(ON)}$ , energy saving, high reliability and uniformity, superior power density and space saving.

## Absolute Max Rating

Symbol	Parameter	Max.	Units
$I_D @ TC = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ <sup>①</sup>	20	A
$I_D @ TC = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ <sup>①</sup>	13	
$I_{DM}$	Pulsed Drain Current <sup>②</sup>	80	
$P_D @ TC = 25^\circ C$	Power Dissipation <sup>③</sup>	208	W
	Linear Derating Factor	1.66	W/°C
$V_{DS}$	Drain-Source Voltage	600	V
$V_{GS}$	Gate-to-Source Voltage	± 30	V
$E_{AS}$	Single Pulse Avalanche Energy @ L=32mH	400	mJ
$I_{AS}$	Avalanche Current @ L=32mH	5	A
$T_J \quad T_{STG}$	Operating Junction and Storage Temperature Range	-55 to + 150	°C

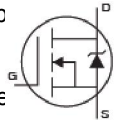
## Thermal Resistance

Symbol	Characteristics	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case <sup>③</sup>	—	0.6	$^{\circ}C/W$
$R_{\theta JA}$	Junction-to-ambient ( $t \leq 10s$ ) <sup>④</sup>	—	62	$^{\circ}C/W$
	Junction-to-Ambient (PCB mounted, steady-state) <sup>④</sup>	—	40	$^{\circ}C/W$

## Electrical Characteristics @ $T_A=25^{\circ}C$ unless otherwise specified

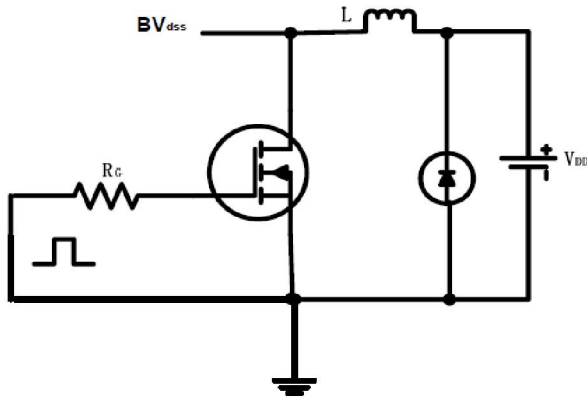
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	600	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	0.2	0.3	$\Omega$	$V_{GS}=10V, I_D = 13A$
		—	0.55	—		$T_J = 125^{\circ}C$
$V_{GS(th)}$	Gate threshold voltage	2	—	4	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
		—	2.4	—		$T_J = 125^{\circ}C$
$I_{DSS}$	Drain-to-Source leakage current	—	—	1	$\mu A$	$V_{DS} = 600V, V_{GS} = 0V$
		—	—	50		$T_J = 125^{\circ}C$
$I_{GSS}$	Gate-to-Source forward leakage	—	—	100	nA	$V_{GS} = 30V$
		-100	—	—		$V_{GS} = -30V$
$Q_g$	Total gate charge	—	90	—	nC	$I_D = 20A,$ $V_{DS}=480V,$ $V_{GS} = 10V$
$Q_{gs}$	Gate-to-Source charge	—	12	—		
$Q_{gd}$	Gate-to-Drain("Miller") charge	—	34	—		
$t_{d(on)}$	Turn-on delay time	—	12	—	ns	$V_{GS}=10V, V_{DS}=380V,$ $R_L=38\Omega,$ $R_{GEN}=4.7\Omega$ $I_D=10A$
$t_r$	Rise time	—	6	—		
$t_{d(off)}$	Turn-Off delay time	—	65	—		
$t_f$	Fall time	—	6	—		
$C_{iss}$	Input capacitance	—	2334	—	pF	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1MHz$
$C_{oss}$	Output capacitance	—	856	—		
$C_{rss}$	Reverse transfer capacitance	—	3	—		

## Source-Drain Ratings and Characteristics

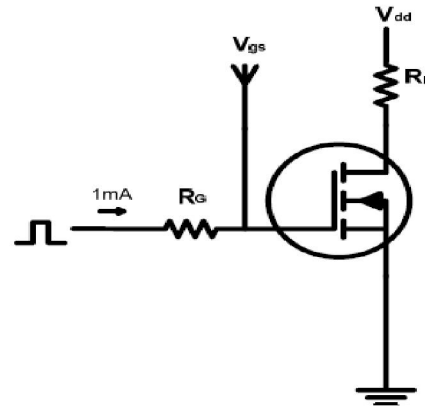
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	20	A	MOSFET symb showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode)	—	—	80	A	
$V_{SD}$	Diode Forward Voltage	—	—	1.2	V	$I_S=20A, V_{GS}=0V$
$t_{rr}$	Reverse Recovery Time	—	480	—	ns	$T_J = 25^{\circ}C, I_F = 20A, di/dt = 100A/\mu s$
$Q_{rr}$	Reverse Recovery Charge	—	10	—	nC	

## Test Circuits and Waveforms

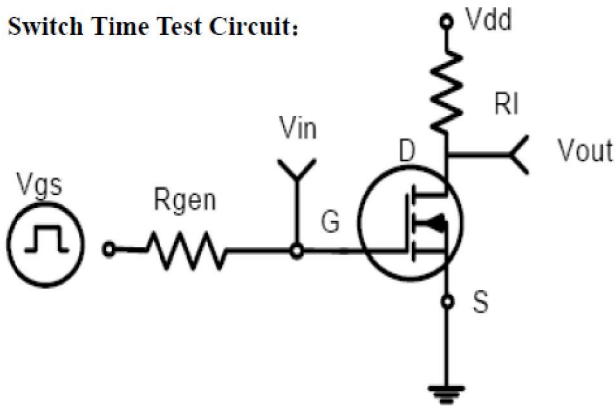
EAS test circuits:



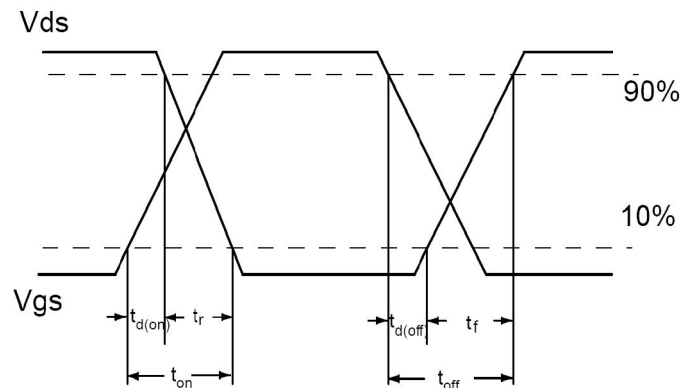
Gate charge test circuit:



Switch Time Test Circuit:



Waveforms:



### Notes:

- ① The maximum current rating is limited by bond-wires.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of  $R_{\theta JA}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$
- ⑤ These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(MAX)} = 150^\circ\text{C}$ .
- ⑥ The maximum current rating is limited by bond-wires.

## Typical Electrical and Thermal Characteristics

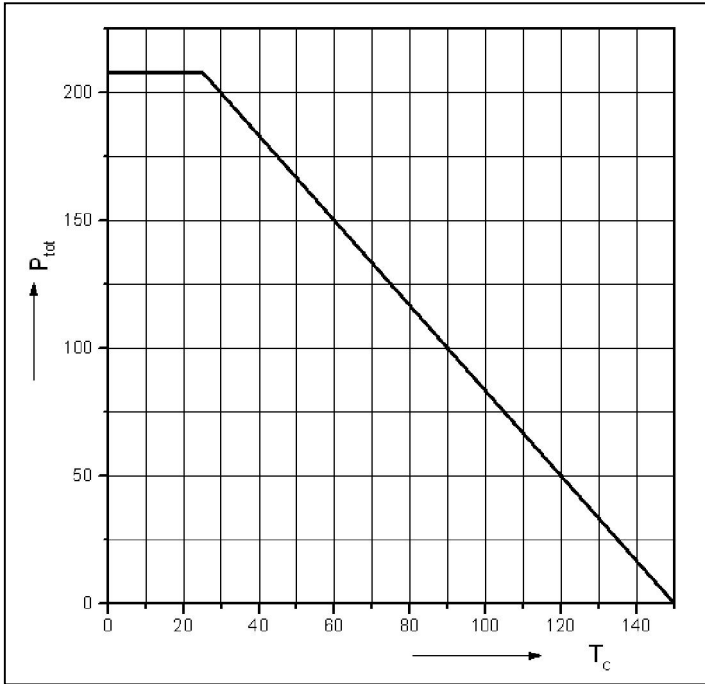


Figure 1: Power dissipation

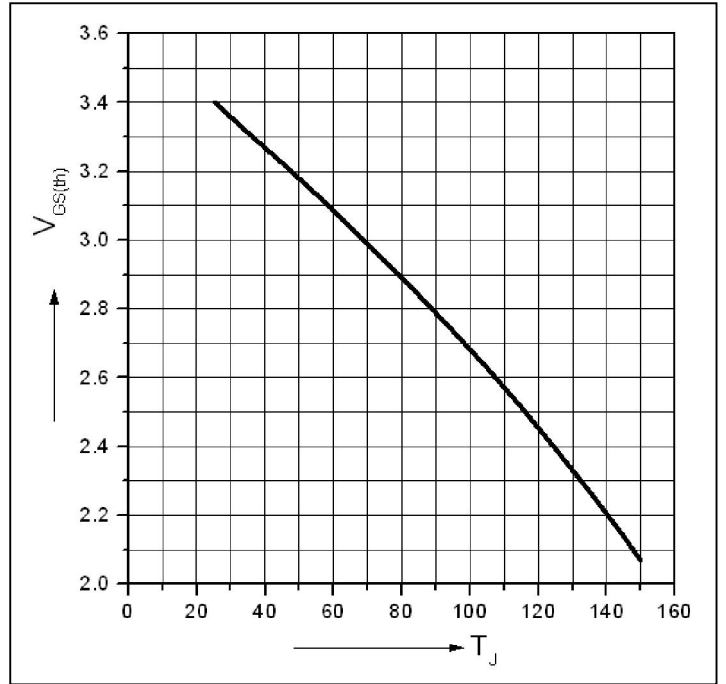


Figure 2: Typ. Gate to source cut-off voltage

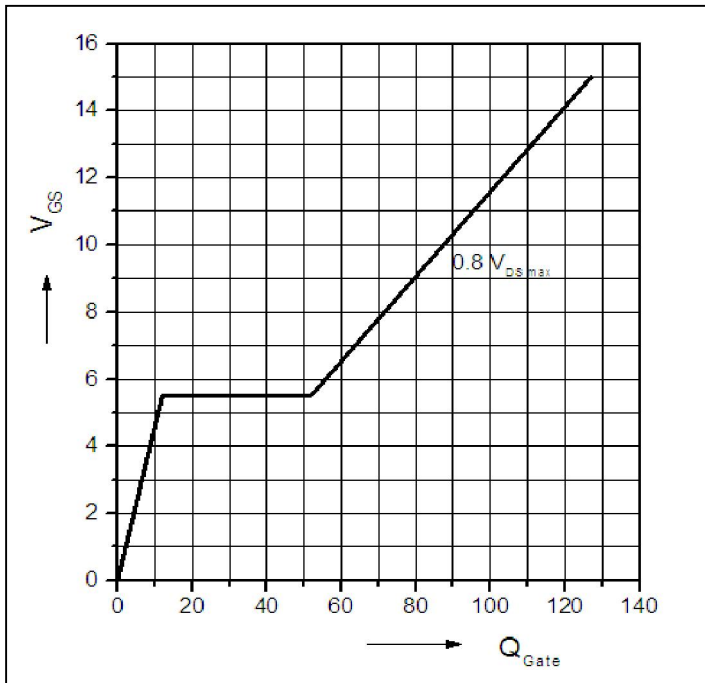


Figure 3: Typ. gate charge

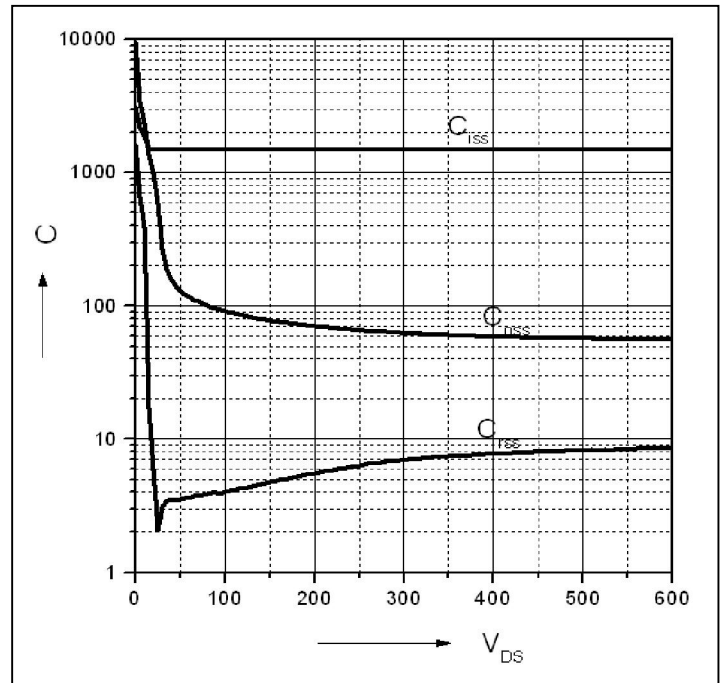


Figure 4: Typ. Capacitances

**Typical Electrical and Thermal Characteristics**

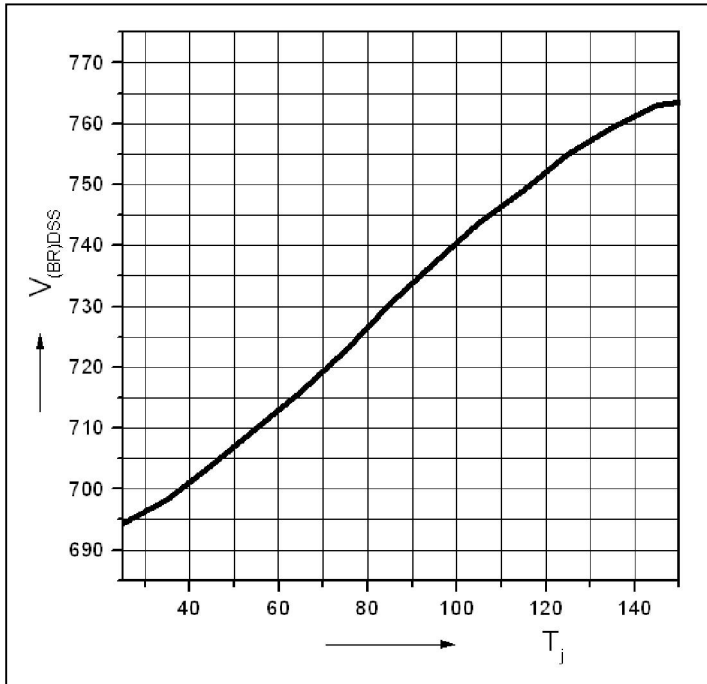


Figure 5. Drain-source breakdown voltage

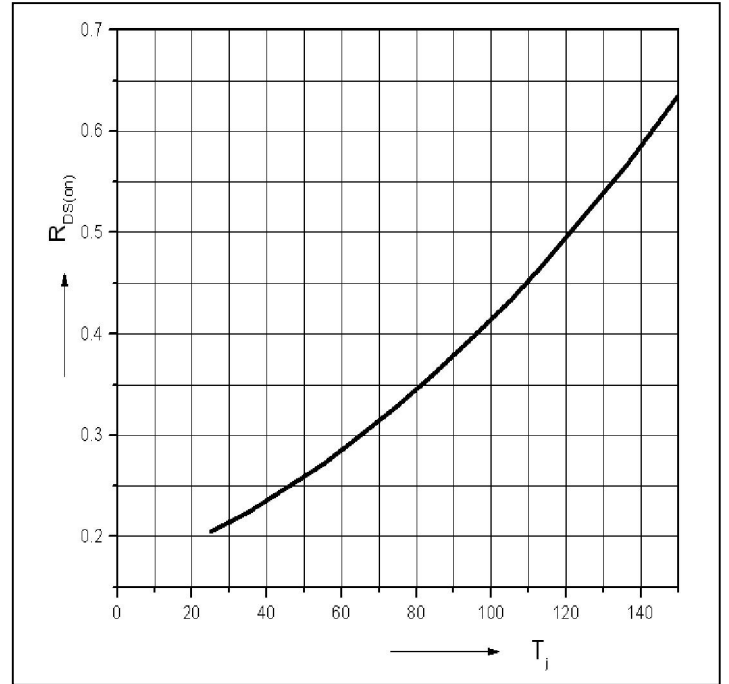


Figure 6. Drain-source on-state resistance





## Ordering and Marking Information

### Device Marking: SSF20N60H

Package (Available)  
TO247  
Operating Temperature Range  
C : -55 to 150 °C

### Devices per Unit

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO247	30	8	240	5	1200

### Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	$T_j=125^{\circ}\text{C}$ to $175^{\circ}\text{C}$ @ 80% of Max $V_{DSS}/V_{CES}/V_R$	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	$T_j=150^{\circ}\text{C}$ or $175^{\circ}\text{C}$ @ 100% of Max $V_{GSS}$	168 hours 500 hours 1000 hours	3 lots x 77 devices